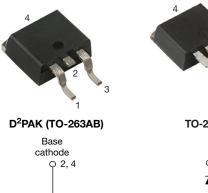
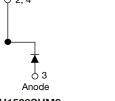
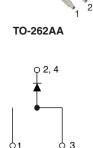


Vishay Semiconductors

Ultra Fast Rectifier, 15 A FRED Pt[®]







VS-ETU1506-1HM3

Anode

N/C

VS-ETU1506SHM3

N/C

PRIMARY CHARACTERISTICS								
Package	D ² PAK (TO-263AB), TO-262AA							
I _{F(AV)}	15 A							
V _R	600 V							
V _F at I _F	1.1 V							
t _{rr} (typ.)	24 ns							
T _J max.	175 °C							
Circuit configuration	Single							

FEATURES

- Low forward voltage drop
- Ultrafast recovery time
- 175 °C operating junction temperature
- Low leakage current
- AEC-Q101 qualified, meets JESD 201 class 1 whisker test



- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION

State of the art, ultralow V_F , soft-switching ultrafast rectifiers optimized for Discontinuous (Critical) Mode (DCM) Power Factor Correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC/DC SMPS 70 W to 400 W

e.g. laptop and printer AC adapters, desktop PC, TV and monitor, games units, and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS				
Repetitive peak reverse voltage	V _{RRM}		600	V				
Average rectified forward current	I _{F(AV)}	T _C = 143 °C	15	٥				
Non-repetitive peak surge current	I _{FSM}	T _C = 25 °C	160	A				
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C				

ELECTRICAL SPECIFICATIONS (T _J = 25 $^{\circ}$ C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V _{BR} , V _R	I _R = 100 μA	600	-	-				
E	V	I _F = 15 A	-	1.35	1.9	V			
Forward voltage	V _F	I _F = 15 A, T _J = 150 °C	-	1.1	1.3				
		V _R = V _R rated	-	0.01	15				
Reverse leakage current	I _R	$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	20	200	μA			
Junction capacitance	CT	V _R = 600 V	-	12	-	pF			
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH			

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DYNAMIC RECOVERY CH	IARACTEF	RISTICS ($T_J = 25$	5 °C unless otherw	/ise speci	fied)		
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS
		$I_F = 1 \text{ A}, \text{ d}I_F/\text{d}t = 1$	00 A/µs, V _R = 30 V	-	-	28	
Reverse recovery time	t _{rr}	T _J = 25 °C		1	40	-	ns
		T _J = 125 °C]	-	87	-	
D. J	I _{RRM}	T _J = 25 °C	I _F = 15 A dI _F /dt = 200 A/μs V _R = 390 V	-	5	-	А
Peak recovery current		T _J = 125 °C		-	9.0	-	A
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	107	-	с
Reverse recovery charge		T _J = 125 °C		-	430	-	U
Reverse recovery time	t _{rr}		I _F = 15 A	-	53	-	ns
Peak recovery current	I _{RRM}	T _J = 125 °C	dI _F /dt = 800 A/µs	-	25	-	А
Reverse recovery charge	Q _{rr}]	V _R = 390 V	-	730	-	nC

THERMAL - MECHANICA	THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C			
Thermal resistance, junction to case	R _{thJC}		-	-	1.51	°C/W			
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	70				
Thermal resistance, case to heat sink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.5	-				
Weight			-	2.0	-	g			
Weight			-	0.07	-	oz.			
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)			
Marking daviag		Case style D ² PAK		ETU1	506SH				
Marking device		Case style TO-262		ETU1506-1H					



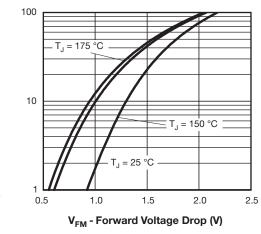


Fig. 1 - Typical Forward Voltage Drop Characteristics

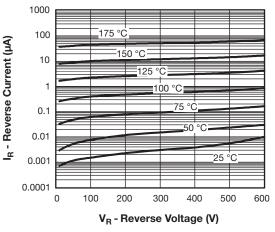


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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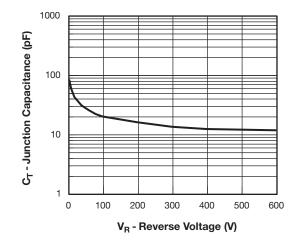


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

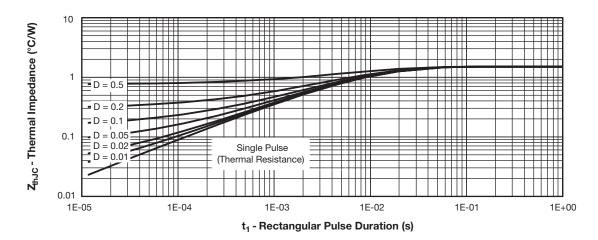
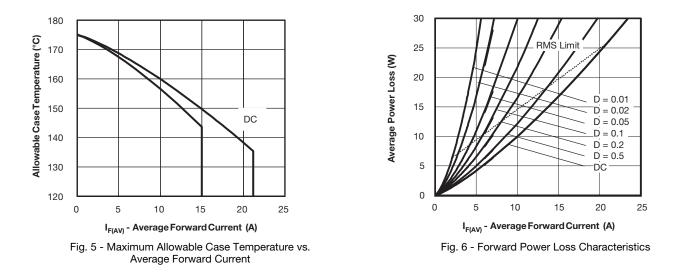


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics



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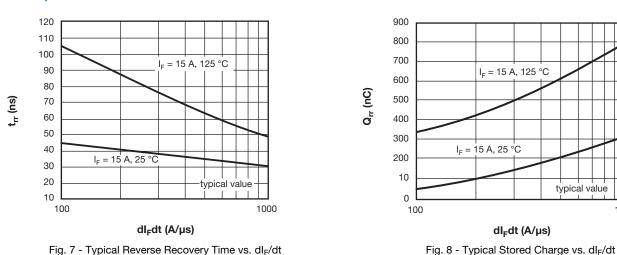
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typical value

1000





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SHAY

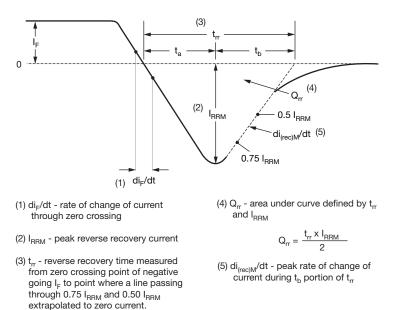
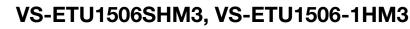


Fig. 9 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

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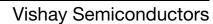
VISHA

Device code	VS-		E	т	U	15	06	S	TRL	н	М3
			2	3	4	5	6	7	8	9	10
	1	-	Visł	nay Sem	niconduc	ctors pro	oduct				
	2 - Circuit configuration E = single diode										
	3	-		TO-220							
	4	-	U =	ultrafas	t recove	ery time					
	5	-	Cur	rent coc	le (15 =	15 A)					
	6	-	Volt	age coo	de (06 =	600 V)					
	7	-	• S :	= D ² PA	K						
		-	• -1	= TO-2	62						
	8	-	• No	one = tu	be (50 p	ieces)					
		- • TRL = tape and reel (left oriented, for D ² PAK package)									
		 • TRR = tape and reel (right oriented, for D²PAK package) 									
	9	-	H =	AEC-Q	101 qua	lified					
	10	-	М3	= halog	en-free,	RoHS-o	complia	nt, and	termina	tions le	ad (Pb)-

ORDERING INFORMATION (Example)								
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION					
VS-ETU1506SHM3	50	1000	Antistatic plastic tube					
VS-ETU1506-1HM3	50	1000	Antistatic plastic tube					
VS-ETU1506STRRHM3	800	800	13" diameter reel					
VS-ETU1506STRLHM3	800	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS								
Dimensions	TO-263AB (D ² PAK)	www.vishay.com/doc?95046						
Dimensions	TO-262AA	www.vishay.com/doc?95419						
	TO-263AB (D ² PAK)	www.vishay.com/doc?95444						
Part marking information	TO-262AA	www.vishay.com/doc?95443						
Packaging information	TO-263AB (D ² PAK)	www.vishay.com/doc?95032						
SPICE model		www.vishay.com/doc?96132						

Outline Dimensions

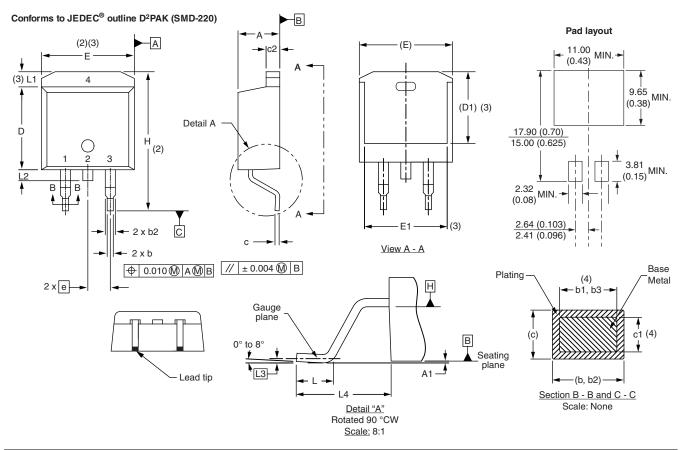


D²PAK

DIMENSIONS in millimeters and inches

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ISHA



SYMBOL	MILLIMETERS		INCHES		NOTES	NOTES SYMBOL				MILLIN	IETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		STWDUL	MIN.	MAX.	MIN.	MAX.	NOTES		
А	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3		
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3		
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3		
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100) BSC			
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625			
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110			
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3		
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070			
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010) BSC			
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208			

Notes

⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994

⁽²⁾ Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

⁽³⁾ Thermal pad contour optional within dimension E, L1, D1 and E1

(4) Dimension b1 and c1 apply to base metal only

⁽⁵⁾ Datum A and B to be determined at datum plane H

⁽⁶⁾ Controlling dimension: inch

⁽⁷⁾ Outline conforms to JEDEC[®] outline TO-263AB

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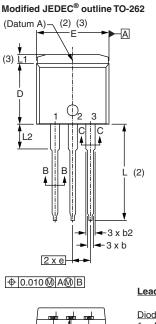
Outline Dimensions

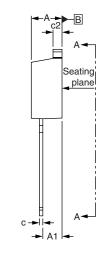


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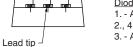
TO-262

DIMENSIONS in millimeters and inches

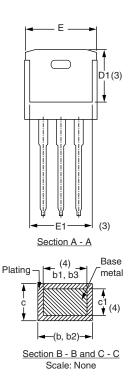




Lead assignments



Diodes 1. - Anode (two die)/open (one die) 2., 4. - Cathode 3. - Anode



	MILLIN	IETERS	INC	NOTEO	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.14 1.65		0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.10) BSC	
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.36	3.36 3.71		0.146	

Notes

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
 ⁽²⁾ Dimension D and E do not include mold flash. Mold flash shall

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

⁽⁵⁾ Controlling dimension: inches

⁽⁶⁾ Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum), D1 (minimum) and L2 where dimensions derived the actual package outline

measured at the outmost extremes of the plastic body $^{(3)}\,$ Thermal pad contour optional within dimension E, L1, D1 and E1

not exceed 0.127 mm (0.005") per side. These dimensions are

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